

Listing of Pending Claims:

- 1.-4. (cancelled)
5. (previously amended) A method for contact printing, comprising the steps of:
- applying a thin film of material to an offset substrate;
 - creating a pattern in the thin film of material by bringing a flexible stamp into contact with the offset substrate, by the steps of:
 - bowing the stamp in a controlled manner;
 - moving the bowed stamp toward the second surface at a predetermined rate until the first surface contacts the second surface at a single point of contact; and
 - continuing to move the bowed stamp toward the offset substrate, under controlled pressure, by the step of pushing air ahead of a moving contact line between the stamp and offset substrate until the single point of contact expands to a circle of desired radius;
 - modifying the patterned film by one or more of the steps of:
 - removing material from the patterned film using a sharp tip;
 - adding material to the patterned film using a sharp tip;
 - removing material from the patterned film by addition of a solvent;
 - removing material from the patterned film using electromagnetic radiation; and
 - curing material in the patterned film to prevent its transfer; and
 - transferring the modified patterned film to a final substrate by bringing the offset substrate into contact with the final substrate.
6. (original) A method according to claim 5 wherein the stamp has a contact angle lower than the contact angle of the offset substrate and the final substrate has a contact angle lower than the contact angle of the offset substrate.

7. (original) A method according to claim 5, further comprising the step of bringing the offset substrate into contact with a second final substrate to transfer any remaining material to the second final substrate.
8. – 9. (cancelled)
10. (withdrawn) A method according to claim 5, the step of bowing comprising rolling a roller against the stamp.
11. (original) A method according to claim 5, further comprising the step of reversing the patterned film by transferring the patterned film to a second offset substrate before transferring it to the final offset substrate by bringing the offset substrate into contact with the second offset substrate.
12. (original) A method according to claim 5, further comprising the step of heating the material before or while applying it to the offset substrate.
13. (original) A method according to claim 5, further comprising the step of heating the patterned film before or during the step of transferring.
- 14.- 15.(cancelled)
16. (withdrawn) An apparatus for bringing first and second surfaces into contact, comprising:
- means for creating a controlled bow in the first surface; and
 - means for moving the first surface toward the second surface at a predetermined rate until the desired amount of contact between the first and second surfaces is achieved.
17. (withdrawn) An apparatus according to claim 16, further comprising an alignment mechanism to control the relative positions of the first and second substrates.

18. (withdrawn) An apparatus according to claim 17, wherein the alignment mechanism includes an optical alignment component.

19. (withdrawn) An apparatus according to claim 16, wherein the means for creating a controlled bow is a pressurization mechanism.

20. (withdrawn) An apparatus according to claim 16, wherein the means for creating a controlled bow is a roller.

21. (withdrawn) An apparatus according to claim 16, wherein the first surface is a stamp made from elastomeric material.

22. (withdrawn) An apparatus according to claim 18, wherein the first surface is optically clear.

23. (previously presented) A method according to claim 5, the step of bowing comprising application of a controlled air pressure difference between the two sides of the stamp.

24. (previously presented) A method according to claim 5, further comprising the step of aligning the stamp and the offset substrates using an alignment mechanism.

25. (previously presented) A method according to claim 24, wherein the alignment mechanism includes an optical alignment component and the stamp is optically clear.

26. (previously presented) A method according to claim 5, the step of modifying the patterned film comprising the step of curing material in the patterned film using a laser.